Overview

HP EliteBook x360 1030 G3



- 1. IR Camera LEDs
- 2. Internal microphones
- 3. IR camera
- 4. FHD Camera
- 5. Webcam LED
- 6. HDMI port (Cable not included.)

Left

- 7. Nano Security lock slot (Lock sold separately.)
- 8. USB Type-C™ with Thunderbolt™
- 9. USB Type-C™ with Thunderbolt™
- 10. Volume up/down
- 11. Touch fingerprint sensor
- 12. Glass clickpad

Overview



- 1. WWAN SIM (Nano)
- 2. Power button

Right

- 3. Audio combo jack
- 4. USB 3.1 Gen 1 charging port

Overview

AT A GLANCE

- All metal CNC Aluminum chassis that is .62 inches (1.58 cm) thin and with a starting weight of 2.76 lbs. (1.25 Kg)
- A 360° convertible notebook with 4 usage modes
- Choice of 8th Generation Intel® Core™ i5, i7 Processors with integrated Intel® HD 620 Graphics
- Display choices include 33.78 cm (13.3") diagonal IPS FHD touch screen or UHD touch screen. Brightness choices up to 700 Nits. Optional Anti-glare screen available. Get added protection in open or public places with the optional HP Sure View integrated privacy screen.
- Ultimate connectivity with 4G/LTE WWAN, WLAN, USB Type-C™, USB Type-A, HDMI and Thunderbolt™ Docking
- Innovative world-facing third mic improves inbound ambient noise cancellation
- Engage teams, clients, and vendors with the crystal-clear audio by Bang & Olufsen and the high-performance HP Premium Collaboration Keyboard
- The new optional HP Rechargeable Active Pen
- Never forget your password with your choice of simple authentication methods, including the IR camera for face recognition and Touch Fingerprint Sensor for Windows Hello
- Choice of solid state drives up to 2 TB
- DDR3 small m Memory up to 16 GB
- Up to 18 hours of battery life¹
- Preinstalled with Windows 10 versions
- Passed MIL-STD 810g testing²
- 1. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.
- 2. MIL-STD-810G testing is pending and is conducted on select HP products. Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

PRODUCT NAME

HP EliteBook x360 1030 G3

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64¹ Windows 10 Home 64¹

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

PROCESSORS

Intel® Core™ i5-8250U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.4 GHz with Intel® Turbo Boost Technology, 6 MB cache, 4 cores)^{2,3,4}

Intel® Core™ i5-8350U vPro™ processor with Intel® UHD Graphics 620 (1.7 GHz base frequency, up to 3.6 GHz with Intel® Turbo Boost Technology, 6 MB cache, 4 cores)^{2,3,4}

Intel® Core™ i7-8550U with Intel® UHD graphics 620 (1.8 GHz base frequency, up to 4 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{2,3,4}

Intel® Core™ i7-8650U vPro™ processor with Intel® UHD graphics 620 (1.9 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)^{2,3,4}

Processor Family

8th Generation Intel® Core™ i5 processor (i5-8350U, i5-8250U models) 8th Generation Intel® Core™ i7 processor (i7-8650U, i7-8550U models)

- 2. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 4. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor.



Features

GRAPHICS

Integrated

Intel® UHD Graphics 620 5

5. HD content required to view HD images.

DISPLAY

Touch

33.8 cm (13.3") diagonal 4K IPS eDP + PSR BrightView LED-backlit touch screen, direct bonded with Corning® Gorilla® Glass 4, 500 cd/m², 100% sRGB (3840 x 2160)^{6,7,8}

HP Sure View Integrated Privacy Screen 13.3" (13.3) diagonal FHD IPS eDP + PSR anti-glare LED-backlit touch screen, direct bonded with Corning® Gorilla® Glass 4, 700 cd/m², 100% sRGB (1920 x 1080)^{6,7,8,9}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS eDP + PSR BrightView LED-backlit touch screen, direct bonded with Corning® Gorilla® Glass 4, 700 cd/m^2 , 100% sRGB (1920 x 1080)^{6,7,8,9}

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare LED-backlit touch screen, direct bonded with Corning® Gorilla® Glass 4, 400 cd/m^2 , 100% sRGB (1920 x $1080)^{6,7,8}$

33.8 cm (13.3") diagonal FHD IPS eDP + PSR BrightView LED-backlit touch screen, direct bonded with Corning® Gorilla® Glass 4, 400 cd/m 2 , 100% sRGB (1920 x 1080) 6,7,8

Displays support

Supports privacy filter
Supports narrow bezel
Direct Bonding 100% Attach

6 HD content required to view HD images.

- 7. Sold separately or as an optional feature.
- 8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 9. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase.



Features

STORAGE AND DRIVES

Primary M.2 Storage M.2 (2280) Solid State Drive

118 GB PCIe® Gen3x2 NVMe™ M.2 SS (Intel® Optane™)¹⁰
128 GB SATA-3 SS TLC¹⁰
256 GB PCIe® NVMe™ SS Value¹⁰
256 GB PCIe® Gen3x4 NVMe™ SS TLC¹⁰
256 GB SATA TLC SED OPAL 2¹⁰

360 GB PCIe® Gen3x4 NVMe™ SS TLC (Intel®)10

512 GB PCIe® Gen3x4 NVMe™ SS TLC10

512 GB PCIe® Gen3x4 NVMe™ SS TLC Opal 210

1 TB PCIe® Gen3x4 NVMe™ SS TLC¹⁰

2 TB PCIe® Gen3x4 NVMe™ SS TLC10

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

16 GB LPDDR3-2133 SDRAM

Memory

8 GB LPDDR3-2133 SDRAM 16 GB LPDDR3-2133 SDRAM

Memory Slots

System runs at 2133 Memory soldered down (customer non-accessible) Supports Dual Channel Memory

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 4.2 Combo, vPro™11 Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 4.2 Combo, non-vPro™11

WWAN

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module¹² Intel XMM 7360 LTE-Advanced (CAT9)¹² Qualcomm Snapdragon X12 LTE-Advanced (CAT9)¹²

NFC

NXP NPC300 Near Field Communication Module

Miracast

Support for Miracast¹³



Features

- 11. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- 12. WWAN is an optional feature and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 13. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 4 Premium Speakers with discrete amps (79Db)

Camera

FHD Camera⁶ IR Camera⁶

6. HD content required to view HD images.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full size

HP Premium Colaboration Keyboard

Backlit

DuraKeys

Spill-resistant

Pointing Device

Clickpad (glass cover) with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - F1 - Display Switching

F2 - Sure View (blank if not supported)

F3 - Brightness Down

F4 - Brightness up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Kybd Backlight

F10 - NumLock

F11 - Wireless

F12 - Calendar

Share/Present

Pick Up/Accept/ Answer/Hold

Hang Up/Decline/ Reject

Delete

Hidden Function Keys

Fn+E - Insert

Fn+W - Pause

Sensors

Accelerometer

Magnetometer

Gyro

ALS (ambient light sensor)*

Hall Sensor

*ALS is disabled when Privacy Mode is turned on



Features

SOFTWARE AND SECURITY

Preinstalled Software BIOS

HP BIOSphere Gen4 14

HP Drive Lock & Automatic Drive Lock

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase 15

Absolute Persistence Module 16

Pre-boot Authentication

HP Wireless Wakeup

Software

HP Native Miracast Support 13

HP LAN-Wireless Protection

HP ePrint Driver + JetAdvantage 17

HP Hotkey Support - CMIT

HP Recovery Manager

HP Jumpstart

HP Support Assistant 18

HP Noise Cancellation Software

Buy Office (Sold separately)

Manageability Features

HP Driver Packs 19

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen2²⁰

Ivanti Management Suite 21

Client Security Software

HP Client Security Suite Gen4 ²² including:

HP Security Manager ²³ (Including Credential Manager, HP Password Manager, HP Spare Key)

HP Fingerprint Sensor

HP Device Access Manager

HP Power On Authentication

Microsoft Defender 24



Features

Security Management

Secure Erase 15

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

SATA 0,1 port disablement (viaBIOS)

RAID configurations 26

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click 27

HP Sure Start Gen4²⁵

HP Sure Run 28

HP Sure Recover 29

Security

MD5 Hash: Please follow the instructions below to access MD5 Hash.

WWAN: TBD WLAN: TBD

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes / No

UEFI version:

- 13. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 14. HP BIOSphere Gen4 requires Intel® or AMD® 8th Gen processors. Features may vary depending on the platform and configurations.
- 15. Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 16. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:
- http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 17. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Print times and connection speeds may vary.
- 18. HP Support Assistant requires Windows and Internet access.
- 19. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 20. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 21. Ivanti Management Suite subscription required.
- 22. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD® 8th generation processors.



Features

- 23. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 24. Microsoft Defender Opt in and internet connection required for updates.
- 25. HP Sure Start Gen4 is available on HP EliteBook products equipped with Intel® 8th generation processors.
- 26. RAID configuration is optional and does require a second hard drive.
- 27. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
- 28. HP Sure Run is available on HP Elite products equipped with 8th generation Intel® or AMD® processors.
- 29. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD processors and requires an open, wired network connection. Not available on platforms with multiple internal storage drives, Intel® Optane™. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.



Features

POWER

Power Supply

65 W USB Type-C™ AC adapter

Primary Battery

HP Long Life 4-cell, 56.2 Wh Li-ion³⁰ Supports battery fast charge

Power Cord

Power cord included is 1.0 m (+/- 0.1 m)

Battery Life

Up to 18 hours (With FHD panel)³¹ Up to 11 hours (With 4K panel)³¹

30. Battery is internal and not replaceable by customer. Serviceable by warranty.

31. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 2.76 lb³² Starting at 1.25 kg³²

Dimensions (w x d x h)

12.04 x 8.07 x 0.62 in 30.58 x 20.5 x 1.58 cm

32. Weight will vary by configuration.



Features

PORTS/SLOTS

Ports

2 Thunderbolt™ (USB Type-C™ connector) 1 USB 3.1 Gen 1 (Charging)

1 HDMI 1.433

1 External Nano SIM slot for WWAN

1 Headphone/microphone combo

33. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers a 1-year limited warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty. Long Life batteries will have same warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 34

34. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

ENVIRONMENTAL & INDUSTRY

HP EliteBook x360 1030 G3 Notebook PC

Eco-Label Certifications	Notebook PC This product has received or is in the process of being certified to the following approvals and may				
& declarations be labeled with one or more of these marks:					
	• IT ECO declaration				
	•US ENERGY STAR®				
	• EPEAT® Gold registered in the Un	ited States. See http://www.epea	t.net for registration status in		
	your country. Search keyword gen		_		
	accessories at http://www.hp.com		J		
System Configuration	_	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
	2.2211		2.12.11		
Normal Operation (Short idle)	6.09 W	6.27 W	6.12 W		
Normal Operation	3.16 W	3.24 W	3.13 W		
(Long idle)					
Sleep	0.82 W	0.84W	0.80 W		
Off	0.30 W	0.34 W	0.29 W		
	NOTE: Energy efficiency data liste model family. HP computers mark U.S. Environmental Protection Age family does not offer ENERGY STA for a typically configured PC fea Microsoft Windows® operating sys	ed with the ENERGY STAR® Logo and the ENERGY STAR® Logo and the ENERGY STAR® specifications, therefore a hard disk drive, a high of the English of the Engli	re compliant with the applicable ations for computers. If a mode n energy efficiency data listed is		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
Normal Operation (Short idle)	21 BTU/hr	21 BTU/hr	21 BTU/hr		
Normal Operation	11 BTU/hr	11 BTU/hr	11 BTU/hr		
(Long idle)		.,			
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr		
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr		
	NOTE: Heat dissipation is calculated attained for one hour.	ted based on the measured watts	s, assuming the service level is		



Technical Specifications

Declared Noise Emissions		Sound Power		ound Drossure	
				Sound Pressure	
(in accordance with		(L _{WAd} , bels)	(L	_{-pAm} , decibels)	
ISO 7779 and ISO 9296)					
Typically Configured – Idle		2.6		15	
Typically configured Tale		2.0		13	
Fixed Disk – Random		3.7		29	
writes				_	
Longevity and Upgrading	This product	can be upgraded, possibly extending it:	s useful life by seve	eral years. Upgradeable	
	features and/or components contained in the product may include:				
	Spare parts are available throughout the warranty period and or for up to 5 years after the end of			to 5 years after the end of	
	production.	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\			
Batteries	This battery(s) in this product comply with EU Direct	ive 2006/66/EC		
	Rattorios uso	d in the product do not contain:			
		ter the 1ppm by weight			
		ater than 20ppm by weight			
	J	area aman Loppin of mongris			
	Battery size: CR2032 (coin cell)				
	Battery type: Lithium				
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -				
	2011/65/EC.				
		duct is designed to comply with the Wa	ste Electrical and E	lectronic Equipment (WEEE)	
	Directive – 2002/96/EC.				
	• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).				
	• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S.</gold>				
	See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd				
	party option store for solar generator accessories at http://www.hp.com/go/options				
	• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.				
	This product contains 0% post-consumer recycled plastic (by wt.)				
		t is 95.1% recycle-able when properly	disposed of at end (
Packaging Materials	External:	PAPER/Corrugated		341 g	
	Internal:	PLASTIC/Polyethylene Expanded - EF	PE	44 g	
		PLASTIC/Polyethylene low density -	LDPE	9 g	
Material Usage	This product	does not contain any of the following s		s of regulatory limits (refer	
		neral Specification for the Environment		-	
	-	np.com/hpinfo/globalcitizenship/envirc	onment/pdf/gse.pd	f):	
	• Asbestos				
	Certain Azo Colorants Costain Prominated Flame Petardants				
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium				
	Cadmium Chlorinated Hydrocarbons				
	Chlorinated Paraffins				
	• Formaldehyde				
	Halogenated Diphenyl Methanes				
	Lead carbonates and sulfates				
	• Lead and Lead compounds				
	Mercuric Oxide Batteries Nickel _ finishes must not be used on the outernal surface designed to be frequently handled or				
	 Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. 				
	• Ozone Depleting Substances				
	• Ozone pepteting substances				



Technical Specifications

l echnical Specifications			
	 Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 		
Packaging Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Formaldehyde - Halogenated Diphenyl Methanes - Lead carbonates and sulfates - Lead and Lead compounds - Mercuric Oxide Batteries - Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. - Ozone Depleting Substances - Polybrominated Biphenyls (PBBs) - Polybrominated Biphenyl Ethers (PBBEs) - Polybrominated Biphenyl Oxides (PBBOs) - Polychlorinated Biphenyl (PCB) - Polychlorinated Terphenyls (PCT) - Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. - Radioactive Substances - Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.		



Global Citizenship Report

Technical Specifications

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

DISPLAYS

bent

Panel LCD 13.3 inch FHD (1920x1080) BrightView WLED D) UWVA 72percent cq 400nits eDP 1.3+PSR ultraslim NB

Outline Dimensions (W x H x 299.76 x 177.24 max. (FPC folding included)

Active Area 293.76 x 165.24

Weight 170g max.

13.3" **Diagonal Size**

Thickness 2.0mm / 4.0mm (PCB) max.

Interface eDP 1.3 w/ PSR (2 lane)

Surface Treatment BV **Touch Enabled** Yes **Contrast Ratio** 800:1

Refresh Rate 60Hz

Brightness 400nits typ. **Pixel Resolution** 1920x1280

Format RGB strip

Backlight LED 72% **Color Gamut Coverage Color Depth** 6 bits

Viewing Angle UWVA 85/85/85/85

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications

Panel LCD 13.3 inch FHD (1920x1080) Anti-Glare WLED UWVA 72percent cg 700nits eDP 1.3+PSR ultraslim NB Privacy

Outline Dimensions (W x H x 300.56 x 178.39 mm (max.)

D)

Active Area 293.86 x 165.34 mm (max.)

Weight 205g (max.)

Diagonal Size 13.3"

Thickness 2.0 mm / 3.9 mm (max.)

Interface eDP 1.4a
Surface Treatment Anti-Glare

Touch Enabled Yes

Contrast Ratio Sharing mode, 600:1 (typ.)

Privacy mode, 150:1 (typ.)

Refresh Rate 120Hz

Brightness Sharing mode, 700 nits (typ.)

Privacy mode, 320 nits (typ.)

Pixel Resolution1920x1080FormatRGB stripBacklightLED

Color Gamut Coverage Sharing mode, 72%

Privacy mode, 60%

Color Depth 6 bits + Hi FRC

Viewing Angle Sharing mode, CR > 10, L/R/U/D, 85/85/85 (typ.)

Privacy mode CR>2, L/R/U/D, 50/50/85/85 (typ.)

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications

Panel LCD 13.3 inch UHD (3840x2160) BrightView WLED D)

UWVA 72percent cg 500nits eDP 1.3+PSR ultraslim NB bent

Outline Dimensions (W x H x 299.26 x 177.51 (FPC folding included)

Active Area 293.76 x 165.24 mm

Weight 190g max.

Diagonal Size 13.3"

Thickness 2.0mm / 4.0mm (PCB) max.

Interface eDP 1.4a PSR (4 lane)

Surface Treatment BV **Touch Enabled** Yes **Contrast Ratio** 1400:1 **Refresh Rate** 60Hz

Brightness 500nits typ.

Pixel Resolution 3840 x 2160 (UHD)

Format RGB strip

Backlight **LED Color Gamut Coverage** 72% **Color Depth** 8 bits

Viewing Angle UWVA 85/85/85/85

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications

STORAGE

SSD 128GB 2280 M2 SATA-3

TLC

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 520 MB/s
Maximum Sequential Write Up To 450 MB/s
Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

M.2 2280

Features DIPM; TRIM; DEVSLP

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 256 GB 2280 M2 PCIe-3x4 Form Factor

SS NVMe TLC

Capacity 256 GB NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (<10 g)

Interface PCIE NVMe Gen3X4

Maximum Sequential Read Up To 2600 MB/s

Maximum Sequential Write Up To 900 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 256 GB 2280 M2 SATA-3 Self Encrypted OPAL2 Three

Layer Cell

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)



Technical Specifications

Weight0.02 lb (<10 g)</th>InterfaceATA-8, SATA 3.0Maximum Sequential Read530 MB/s ~ 560 MB/sMaximum Sequential Write500 MB/s ~ 530 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 256 GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 360 GB
NAND Type MLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 1700 MB/s
Maximum Sequential Write Up To 600 MB/s
Togical Blocks 703,282,608

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 360 GB 2280 PCIe-3x4 NVMe Three Layer Cell Form Factor 0.02 lb (10 g)
Capacity 360 GB
NAND Type MLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIE NVMe Gen3X4
Maximum Sequential Read Up To 1700 MB/s
Maximum Sequential Write Up To 600 MB/s
Logical Blocks 703,282,608



Technical Specifications

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 512 GB 2280 M2 PCIe-3x4 Form Factor SS NVMe TLC Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 2800 MB/s ~ 2900 MB/s

Maximum Sequential Write 1000 MB/s ~ 1800 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 512 GB 2280 M2 SATA-3 Three Layer Cell Federal Information Processing Standard Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ACS-3, SATA 3.2
Maximum Sequential Read Up To 530 MB/s
Maximum Sequential Write Up To 400 MB/s
Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features TCG Opal 2.0; FIPS, DIPM; TRIM; DEVSLP

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications

SSD 512 GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Cell
 Drive Weight
 0.02 lb (10 g)

 Capacity
 512 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2900 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TCG Opal2, TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

SSD 1TB 2280 PCIe-3x4 NVMe Form Factor Three Layer Cell single-sided Capacity

Form Factor 0.02 lb (10 g)

Capacity 1TB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up To 2900 MB/s

Maximum Sequential Write Up To 2000 MB/s
Logical Blocks 2,000,409,263

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

SSD 2TB 2280 PCIe-3x4 NVMe Form Factor
Three Layer Cell single-sided Capacity

Form Factor M.2 2280
Capacity 2TB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2900 MB/sMaximum Sequential WriteUp To 2100 MB/sLogical Blocks3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security, DIPM; TRIM; DEVSLP

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 50 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

NETWORKING/COMMUNICATIONS

Intel 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth®

(2x2) WiFi and Bluetooth⁶ 4.2 Combo¹ Vpro **Wireless LAN Standards**

IEEE 802.11a IEEE 802.11b IEEE 802.11g

IEEE 802.11n IEEE 802.11ac

Interoperability
Frequency Band

Wi-Fi certified **802.11b/g/n**

• 2.402 - 2.482 GHz

802.11a/n

• 4.9 - 4.95 GHz (Japan)

5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz

• 5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCSO ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation Direct Sequence Spread SpectrumBPSK, QPSK, CCK, 16-QAM, 64-QAM,

256-0AM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

• Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +14dBm minimum

• 802.11g : +12dBm minimum • 802.11a : +12dBm minimum

802.11n HT20(2.4GHz): +12dBm minimum
802.11n HT40(2.4GHz): +12dBm minimum
802.11n HT20(5GHz): +10dBm minimum
802.11n HT40(5GHz): +10dBm minimum
802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated)

• Idle mode 50 mW (WLAN unassociated)

Technical Specifications

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power

management 802.11 compliant power saving mode

Receiver Sensitivity ³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to

support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Weight Type 2230 : 2.8g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant **Frequency Band** 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH)BLE: 0~39 (2 MHz/CH)

Data Rates and

Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

Throughput

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps



Technical Specifications

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mWPeak (Rx) 230 mWSelective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826Low Voltage Directive IEC950UL, CSA, and CE

Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Intel 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo¹ Non-Vpro

Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11g

IEEE 802.11n IEEE 802.11ac

Interoperability Wi-Fi certified Frequency Band 802.11b/q/n

• 2.402 - 2.482 GHz

802.11a/n

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5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
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Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation Direct Sequence Spread SpectrumBPSK, QPSK, CCK, 16-QAM, 64-QAM,

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• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

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WAPI

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• 802.11g : +12dBm minimum • 802.11a : +12dBm minimum

802.11n HT20(2.4GHz): +12dBm minimum
802.11n HT40(2.4GHz): +12dBm minimum
802.11n HT20(5GHz): +10dBm minimum
802.11n HT40(5GHz): +10dBm minimum
802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)Idle mode 50 mW (WLAN unassociated)

• Connected Standby 10mW

• Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power

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BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

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asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption
Electrical Interface

Peak (Tx) 330 mWPeak (Rx) 230 mWSelective Suspend 17 mW

Divista eth Coftuero

USB 2.0 compliant

Bluetooth Software

Microsoft Windows Bluetooth Software

Supported Link Topology



Technical Specifications

Power Management

Microsoft Windows ACPI, and USB Bus Support

Certifications

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328, ETS 300 826Low Voltage Directive IEC950UL, CSA, and CE

Power Management

Mark

Certifications

BT4.1-ESR 5/6/7 Compliance

Bluetooth Profiles
Supported

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 –Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

HP lt4132 LTE/HSPA+ 4G Mobile Broadband

Module¹

bands

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz

E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

Technology/Operating

3GPP Release 10 LTE Specification CAT.4, 20MHz BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm



Technical Specifications

GPRS 1900/1800: 29.5 dBm

GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions (Length x 42 x 30 x 2.3 mm

Width x Thickness)

 Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP lt4210 4G Module1

Technology/Operating

bands

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13

upper), 700 (Band 17 lower), 800 (Band 20), 700 (Band 28).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5),

900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 10 LTE Specification CAT.4, 20MHz BW, WCDMA R99, 3GPP

Release 5, 6, 7 and 8 UMTS Specification 1xEVDO Release 0, A and B.

E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 -

MSC9

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

CDMA 1xRTT: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rel.A: 3.1 Mbps (Download), 1.8 Mbps (Upload) EVDO Rel.B: 14.7 Mbps (Download), 5.4Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm 1xRTT/EVDO: 24dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm



Technical Specifications

GPRS 900/850: 32.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average)
HSPA+: 1,100 mA (peak); 800 mA (average)
1xRTT/EVDO: 1,000 mA (peak); 700 mA (average)
E-GPRS: 2,800 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6.2 g

Dimensions (Length x Width x Thickness) 42 30 x 2.3 mm

 Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM™ 7360 LTE-Advanced CAT9¹

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band

41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release

5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

MHz

Technical Specifications

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8g

Dimensions (Length x Width x Thickness)

30 x 2.3 mm

1.

Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Near Field Communications Controller (optional) Dimensions (L x W x H)

Module 17 mm by 10 mm by 2.0 mm

Chipset

NPC300

System interface

I2C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode (1) ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Technical Specifications

Card Emulation (PICC-VICC) ISO/IEC 14443 A

Mode (1) ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer

Raw RF Data Rates 106, 212, 424, 848 kbps

Operating temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity 10-90% operating

Supply Operating voltage 2.97 to 5.5 Volts

I/O Voltage 1.8V or 3.3V

Power Consumption (Booster enable, VBAT= 3.3V, VCC BOOST = 5V) Mode Power Consumption, Typical

Polling 7.3 mA

Detected Test Tag Type 1 32.9 mA

Detected Test Tag Type 2 70.7 mA

Detected Test Tag Type 3 79.2 mA

Detected Test Tag Type 4 64.9 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.

Technical Specifications

POWER

AC Adapter 65 Watt nPFC Slim USB type C Straight 1.8m (MissPiggy)

Dimensions 88.0x53.5x21.0mm Weight 220g +/- 10g Input 100 to 240 VAC

> **Input Efficiency** Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec:

> > 5V:81.5% 9V:86.7% 12V:88.0% 15V:89.0% 20V:89.0% 48 ~ 63 Hz

Input frequency range **Input AC current** Max. 1.7 A at 90 VAC

Output power 5V/15W

9V/27W 12V/60W 15V/65W 20V/65W

DC output 5V / 9V / 12V / 15V / 20V Hold-up time 5ms at 115 Vac input

Output current limit < 8.0A

Connector **USB Type-C**

Environmental Design Operating temperature 32° to 95° F (0° to 35° C) -4° to 185° F (-20° to 85° C)

Non-operating (storage)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

Output

CE Mark- full compliance with LVD and EMC directives; Worldwide safety standards-IEC950, EN60950, UL1950, Class 1, SELV; Agency approvals-C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCIB, NOM-1 NYCE; MTBF- over 200,000 hours at 25°C ambient condition.



Technical Specifications

Battery ME 4 Cell WHr 50 Long Life -PL Fast Charge

Dimensions $(H \times W \times L)$

0.188kg (0.415 lb)

Weight

4cell Lithium-Ion Polymer cell / 385784

Energy

Cells/Type

Voltage 8.8V/7.7V

4.0 x 96.62 x231.8 mm (0.157 x3.804 x9.126 inch)

Amp-hour capacity

Watt-hour capacity

6.175Ah(min.)/6.5Ah(typ.) 47.5Wh(min.)/50Wh(typ.)

Operating (Charging)

32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 122° F (-10° to 60° C)

Fuel Gauge LED

Temperature

No No

Optional Travel Battery

Available

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

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Туре	Description	Part #
Cases	HP Slim Ultrabook Top Load	F3W15AA#xxx
	HP Exec Midnight 15.6" Backpack	1KM16AA#xxx
Docking	HP Thunderbolt Dock 120W G2	2UK37AA#xxx
	HP TB Dock G2 w/ Combo Cable	3TR87AA#xxx
	HP TB Dock 120W G2 w/ Audio	3YE87AA#xxx
	HP Thunderbolt Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP USB-C Universal Dock	1MK33AA#xxx
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock NF	3DV65AA
	HP USB-C Dock G4	3FF69AA#xxx
	HP USB-C Mini Dock	1PM64AA#xxx
	HP USB Travel Dock	T0K30AA#xxx
	HP Elite 90W Thunderbolt 3 Dock	1DT93AA#xxx
	HP Hot Desk Stand (up to 32" monitor)	W3Z73AA#xxx
	HP Hot Desk Stand Monitor Arm (for use with W3Z73AA; supports two 24" monitors)	W3Z74AA#xxx
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP Slim USB Keyboard and Mouse	T6T83AA#xxx
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
	HP USB Essential Keyboard and Mouse	H6L29AA#xxx
	HP Conferencing Keyboard	K8P74AA#xxx
	HP USB Collaboration Keyboard	Z9N38AA#xxx
	HP Wireless Collaboration Keyboard	Z9N39AA#xxx
	HP Comfort Grip Wireless Mouse	H2L63AA#xxx
	HP X4000b Bluetooth Mouse	H3T50AA#xxx
	HP 3-Button USB Laser Mouse	H4B81AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP Wireless Premium Mouse	1JR31AA#xxx
	HP USB Premium Mouse	1JR32AA#xxx
	HP Elite Presenter Mouse	2CE30AA#xxx
	HP Stereo 3.5mm Headset	T1A66AA#xxx
	HP Stereo USB Headset	T1A67AA#xxx
	HP USB-C to USB 3.0 Adapter	N2Z63AAA#xxx
	HP USB-C to USB-A Hub	Z6A00AA#xxx
	HP USB-C to DP	N9K78AA#xxx
	HP USB-C to VGA	N9K76AA#xxx
	HP USB-C to RJ45 Adapter	V7W66AA

Options and Accessories (sold separately and availability may vary by country)

	HP EliteDisplay S270n 27-inch 4K Monitor	2PD37AA
	HP EliteDisplay S240n 23.8-inch Monitor	W9A88AA
	HP EliteDisplay E273m 27-inch Collaboration Monitor	1FH51AA
	HP EliteDisplay E273q 27-inch QHD Monitor	1FH52AA
Displays	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP UC Wireless Duo Headset	W3K09AA#xxx
	HP UC Wireless Mono Headset	W3K08AA#xxx
	HP UC Wired Headset	K7V17AA#xxx
ucc	HP UC Speaker Phone	K7V16AA#xxx
	HP Nano Dual-Head Keyed Cable Lock	1AJ41AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
Storage	HP USB External DVDRW Drive	F2B56AA#xxx
	HP 16 GB DDR4-2666 SODIMM	TBD
	HP 8 GB DDR4-2666 SODIMM	TBD
Memory	HP 4 GB DDR4-2666 SODIMM	TBD
	HP USB-C Notebook Power Bank	1TZ86AA#xxx
	HP 65W USB-C Slim Power Adapter	3PN48AA
Power	HP 65W USB-C Power Adapter	1HE08AA#xxx
	HP USB-C to USB-A Hub	Z6A00AA#xxx
	HP Rechargeable Active Pen	4KL69AA
	HP USB 3.0 to Gigabit Adapter	N7P47AA#xxx
	HP HDMI to VGA	H4F02AA#xxx
	HP HDMI to DVI	F5A28AA#xxx



Options and Accessories (sold separately and availability may vary by country)

Docking station model	Total number of supported displays (incl. the notebook display)	Max.resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station	3	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays into DP
HP Elite 120W TB3 Dock	3	Dual 4K @ 60Hz	"2xDP, 1xVGA, 1xTB,	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP Elite USB-C Dock G4	3	"Dual 2K @ 60Hz	1xUSB-C alt- mode"	
HP USB-C Universal Dock	3	Single 4K @ 60Hz (3840 x 1440)"	1xHDMI, 2xDP	
HP USB-C Travel Dock	2	Dual 4K @ 60Hz	2xDP	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 5K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time



Summary of Changes

Date of change:	Version History:		Description of change:
June 12, 2018	v1 to v2	Updated	Touch enabled displays section
June 28, 2018	v2 to v3	Added	Environmental tab
July 5, 2018	v3 to v4	Updated	Sensors section footnote
July 11, 2018	v4 to v5	Updated	Warranty
August 6, 2018	v5 to v6	Removed	Software Velocity
August 23, 2018	V6 to v7	Updated	WWAN section
August 31, 2018	V7 to v8	Added	Networking section and Audio sections
November 2, 2018	V8 to v9	Updated	At a glance Passed MIL-STD
December 10, 2018	V9 to V10	Updated	Memory section
February 12, 2019	V10 to V11	Updated	Active Pen

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